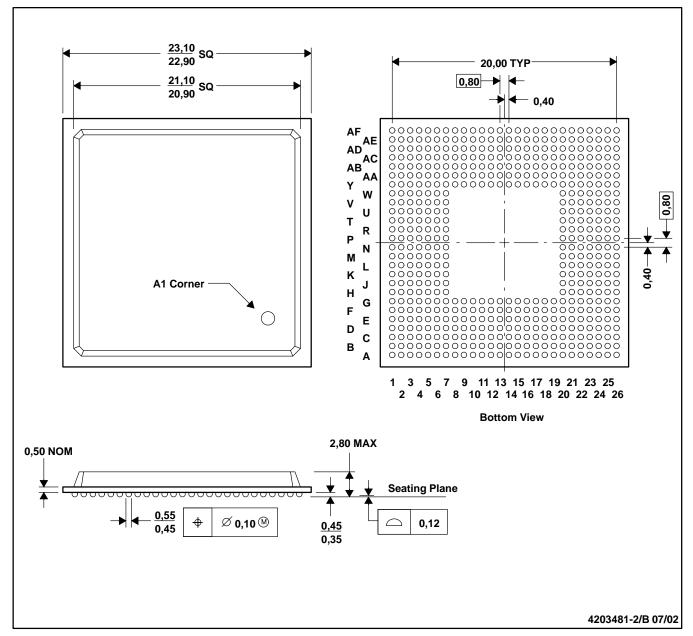
GDK (S-PBGA-N532)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Flip chip application only.

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Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

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